IPC ASSOCIATION CON ELECTRONICS INC		Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Materi					ials and Mfg Information				
upplier In	nformation									, ,					
Company name*			Company unique ID			J	Unique ID Authority					Response Date*			
onsemi											2024-05-15				
Contact Name	e	Title - Contact			I	Phone - Contact*				Email - Contact*					
Product-Env-	-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorized Ro	epresentative*	Title - Representative			I	Phone - Representative*				Email - Representative*					
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Re	equester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	e Vers	ion	Manufacturing Site		V	eight*	UOM	Unit Type
		NCV4275CDS33R4G		3.3V/450mA LDO			2024-05-15				1	517.9136	mg	Each	
Ianufactu	ring Proccess Inform	ation													
Terminal Plating / Grid Array Material Terminal Base A			Alloy J-STD-020 MSL Rating Peak			Peak Prod	k Process Body Temperature Max Time at Peak Temp				Temperatu	re Numb	er of Reflow Cyc	eles	
Ma	atte Tin (Sn) - annealed	(CU Alloy	1			260		C	30		second	s 3		
omments															
vel 1 - maxir	mum time at peak tempera	ture during sol	dering is 10-3	0 seconds											
or more info	ormation regarding materia	al composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominal contains a RoHS restricted substance inexcess encompass all such components. Supplier certi as of the date that Supplier completes this for Company acknowledges that Supplier may ha independently verified information provided by certification in this paragraph. If the Company	ted biphenyls and/or polybrominated dipheny of an applicable quantity limit, please indicate fies that it gathered the information it provident. Supplier acknowledges that Company will we relied on information provided by others in the supplier agrees that, at a minimum and the Supplier enter into a written agreements ource of the Supplier's liability and the Com-	2011/65/EU and implemented by the laws of the End ethers (each a "RoHS restricted substance") in except the below which, if any, RoHS exemption you believe in this form using appropriate methods to ensure rely on this certification in determining the compliant completing this form, and that Supplier may not have its suppliers have provided certifications regarding ent with respect to the identified part, the terms and capany's remedies for issues that arise regarding information in the content of the content with the supplier of the identified part, the terms and capany's remedies for issues that arise regarding information in the content of t	sess of the applicable quantity limit identified able may apply. If the part is an assembly with low its accuracy and that such information is true annee of its products with European Union member ave independently verified such information. However, their contributions to the part, and those certifications of that agreement, including any warr	bove. If a homogeneous material within the part ver level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. It is involved in situations where Supplier has not ations are at least as comprehensive as the ranty rights and/or remedies provided as part of						
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.19	mg	Supplier	Silicon (Si)	7440-21-3		0.19	mg
Die Attach	11.31	mg	A	Lead (Pb)	7439-92-1	7a	10.7445	mg
			Supplier	Tin (Sn)	7440-31-5		0.5655	mg
Lead Frame	851.27	mg	В	Nickel (Ni)	7440-02-0		2.5538	mg
			Supplier	Copper (Cu)	7440-50-8		848.7162	mg
Mold Compound-Black	727.2536			Epoxy resin	proprietary data		36.3627	mg
			Supplier	Phenolic Resin	Proprietary Data		36.3627	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		14.5451	mg
			Supplier	Carbon Black (C)	1333-86-4		3.6363	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		636.3469	mg
Plating	27.15	mg	Supplier	Tin (Sn)	7440-31-5		27.15	mg
Wire Bond - Cu	0.74	mg	Supplier	Copper (Cu)	7440-50-8		0.74	mg